

Light is OSRAM



15.09.2016

Dear Customer,

please find attached our OSRAM OS PCN:

OS-PCN-2016-020-A Standardization of wafer processing and chip design of High Power Pulsed Laser Diodes

Important information for your attention:

Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **20.10.2016**.

OSRAM OS aligns with the widely-recognized JEDEC STANDARD "JESD46-B", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".

Your prompt reply will help OSRAM OS to assure a smooth and well executed transition. If OSRAM OS does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

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Your attention and response to this matter is highly appreciated.

Please direct your inquiry to your local Sales office.

OS-PCN-2016-020-A

Standardization of wafer processing and chip design of High Power Pulsed Laser Diodes

Subject of change:	Standardization of wafer processing and chip design of High Power Pulsed Laser Diodes	
Affected products	SPL LL90_3 SPL PL90_3 SPL PL90	
Reason for change:	Utilization of state of the art LED wafer processing equipment to increase tooling redundancy Standardization of chip design to reduce production complexity	
Description of change	<u>Current status</u>	<u>New status</u>
n-contact thickness	typ. 500nm	typ. 1100nm
n-contact size	typ. 400 x 600 nm (SPL LL90_3, SPL PL90_3) typ. 600 x 600 nm (only SPL PL90)	typ. 340 x 540 nm
chip size (only SPL PL90)	typ. 600 x 600 nm	typ. 400 x 600 nm
For further details, please refer to 2_cip_OS-PCN-2016-020-A		
Product identification:	Date code	
	Final qualification report	November 2016
	Samples	available
	Production release	January 2017
Time schedule:	Start of delivery	31.07.2017*) *) earlier delivery may be possible if released by customer
	Last time order date	31.01.2017**) **) last date for ordering products of current status
	Last shipment of existing design	30.06.2017

Assessment:

no changes in epitaxial growth
no changes in chip processing (singulation, mirror technology)
no change in product data sheet
no change in product reliability

Documentation:

2_cip_OS-PCN-2016-020-A

Customer approval form

OS-PCN-2016-020-A

Standardization of wafer processing and chip design of
High Power Pulsed Laser Diodes

Please list product(s) affected in your application(s):

Please check the appropriate box below:

Agreement: We agree with the proposed change and accept start of the shipment upon availability of the new version.

Objections: We have objections:

Information requested: We need the following information:

Samples requested: We need the following samples:

Sender

Company:

Address / Location:

Signature:

Date:

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GmbH

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OSRAM
Opto Semiconductors

Products Affected by Product Change Notification

Number: OS-PCN-2016-020-A

Name: Standardization of wafer processing and chip design of High Power Pulsed Laser Diodes

Release Date: 9/14/2016

Response Due Date: 10/20/2016

Implementation Date: 7/31/2017

<i>Product</i>	<i>QNumber</i>	<i>QNumber Description</i>	<i>Part Number</i>
SPL PL90	Q62702P1760	SPL PL90	SPLPL90
	Q62702P5353	SP L PL90-3	SPL PL90-3